Unit: mm

TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π-MOSIII)

2SK2749

Chopper Regulator, DC-DC Converter and Motor Drive Applications

• Low drain–source ON resistance $: R_{DS (ON)} = 1.6 \Omega (typ.)$

 $\bullet \quad \mbox{High forward transfer admittance} \quad \mbox{:} \; |\,Y_{fs}\,| \, = 5.0 \; S \; (\mbox{typ.})$

• Low leakage current : $IDSS = 100 \mu A (max) (VDS = 720 V)$

• Enhancement-mode $: V_{th} = 2.0 \sim 4.0 \text{ V (V}_{DS} = 10 \text{ V, I}_{D} = 1 \text{ mA})$

Maximum Ratings (Ta = 25°C)

Characteri	stics	Symbol	Rating	Unit	
Drain-source voltage		V_{DSS}	900	V	
Drain-gate voltage (R _{GS} = 20 kΩ)		V_{DGR}	900	V	
Gate-source voltage		V_{GSS}	±30	٧	
Drain current	DC (Note 1)	I _D	7	Α	
	Pulse (Note 1)	I _{DP}	21		
Drain power dissipatio	n (Tc = 25°C)	P_{D}	150	W	
Single pulse avalanche energy (Note 2)		E _{AS}	682	mJ	
Avalanche current		I _{AR}	7	Α	
Repetitive avalanche energy (Note 3)		E _{AR}	15	mJ	
Channel temperature		T _{ch}	150	°C	
Storage temperature range		T _{stg}	-55~150	°C	

Weight: 4.6 g (typ.)

Thermal Characteristics

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R _{th (ch-c)}	0.833	°C / W
Thermal resistance, channel to ambient	R _{th (ch-a)}	50	°C/W

Note 1: Please use devices on condition that the channel temperature is below 150°C.

Note 2: V_{DD} = 90 V, T_{ch} = 25°C (initial), L = 25.5 mH, I_{AR} = 7 A, R_G = 25 Ω

Note 3: Repetitive rating: Pulse width limited by maximum channel temperature

This transistor is an electrostatic sensitive device.

Please handle with caution.

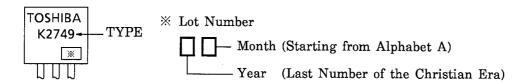
Electrical Characteristics (Ta = 25°C)

Charac	teristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	rrent	I _{GSS}	V _{GS} = ±25 V, V _{DS} = 0 V	_	_	±10	μΑ
Gate-source bre	eakdown voltage	V (BR) GSS	$I_G = \pm 10 \ \mu A, \ V_{DS} = 0 \ V$	±30	_	_	V
Drain cut-off cur	rent	I _{DSS}	V _{DS} = 720 V, V _{GS} = 0 V	_	_	100	μΑ
Drain-source br	eakdown voltage	V _{(BR)DSS}	I_D = 10 mA, V_{GS} = 0 V	900	_	_	V
Gate threshold v	roltage	V_{th}	V _{DS} = 10 V, I _D = 1 mA	2.0	_	4.0	V
Drain-source Ol	N resistance	R _{DS} (ON)	V _{GS} = 10 V, I _D = 3.5 A	_	1.6	2.0	Ω
Forward transfer	admittance	Y _{fs}	V _{DS} = 10 V, I _D = 3.5 A	1.25	5.0	_	S
Input capacitanc	е	C _{iss}		_	1500	_	
Reverse transfer	capacitance	C _{rss}	V _{DS} = 25 V, V _{GS} = 0 V, f = 1 MHz	_	30	_	pF
Output capacitance		C _{oss}		_	140	_	
Switching time	Rise time	t _r	V_{GS} V_{GS} V_{OV} V_{DD} V_{DD} V_{DD}	_	35	_	- ns
	Turn-on time	t _{on}		_	80		
	Fall time	t _f		_	50		
	Turn-off time	t _{off}	Duty $\leq 1\%$, $t_{\mathbf{W}} = 10 \mu s$	_	220		
Total gate charge (gate-source plus gate-drain)				55	_		
Gate-source charge		Q _{gs}	$V_{DD} \approx 400 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 7 \text{ A}$		30	_	nC
Gate-drain ("miller") Charge		Q_{gd}			25	_	

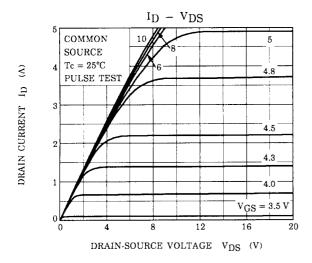
Source-Drain Ratings and Characteristics (Ta = 25°C)

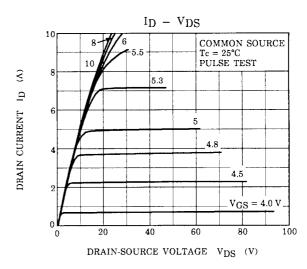
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I _{DR}	_	_	-	7	Α
Pulse drain reverse current (Note 1)	I _{DRP}	_	_	-	21	Α
Forward voltage (diode)	V_{DSF}	I _{DR} = 7 A, V _{GS} = 0 V	_	_	-1.9	V
Reverse recovery time	t _{rr}	I _{DR} = 7 A, V _{GS} = 0 V	_	1400	_	ns
Reverse recovery charge	Q_{rr}	dl _{DR} / dt = 100 A / μs	_	14	_	μC

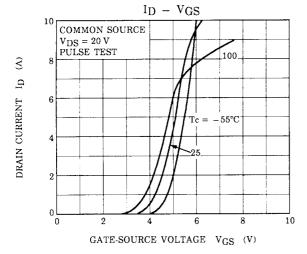
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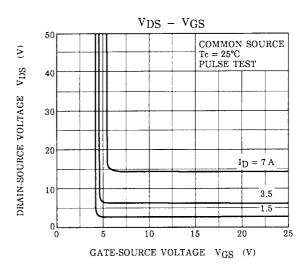


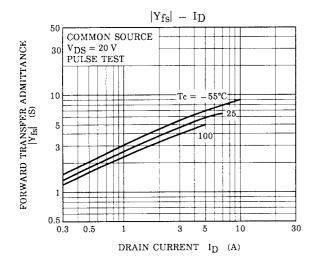
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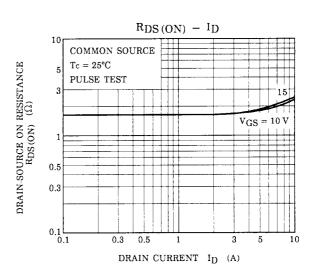




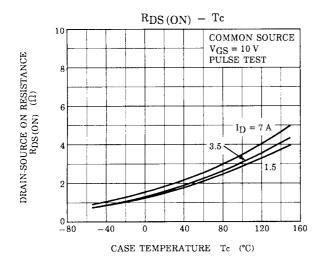


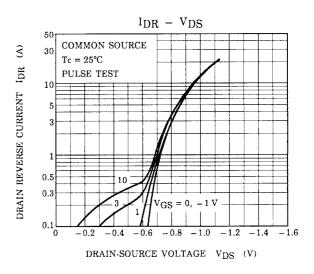


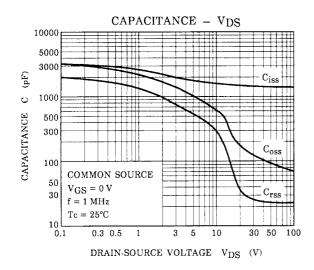


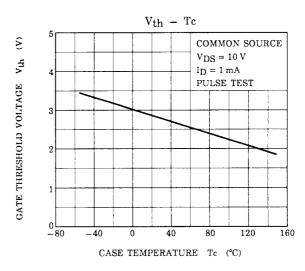


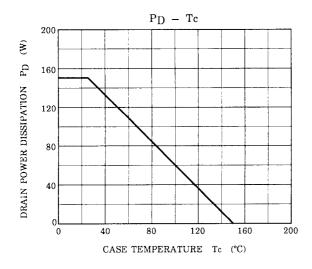
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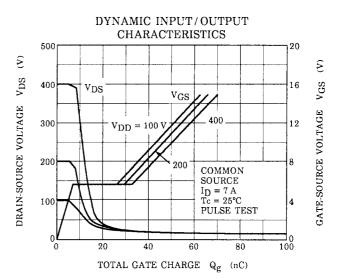




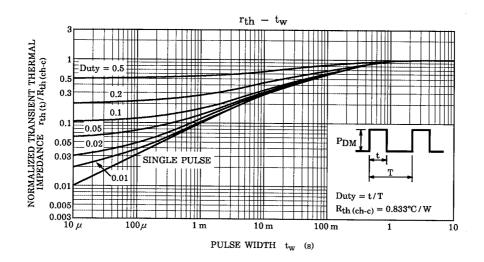


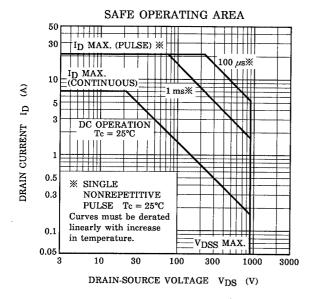


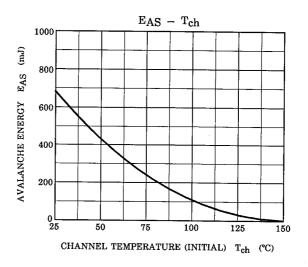


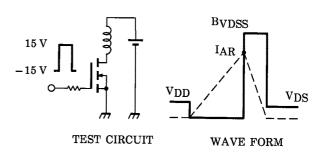


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$$\begin{aligned} &R_G = 25~\Omega \\ &V_{DD} = 90~V,~L = 25.5~mH \end{aligned} \qquad E_{AS} = \frac{1}{2} \cdot L \cdot I^2 \cdot \left(\frac{B_{VDSS}}{B_{VDSS} - V_{DD}} \right) \end{aligned}$$

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